



Global multicarrier

# eSIM

(plan01s)

## IoT Connectivity and Platform Services

Soracom provides IoT connectivity and platform services to over 25,000 businesses and over 6M connections, with solutions for every challenge in IoT. We're focused on making it easy to connect M2M devices at scale, with a powerful IoT SIM that provides connectivity in 180 countries. Soracom provides direct integrations with the world's leading cloud platforms, making it easy to transmit data from your device to AWS, Google Cloud Platform, or Microsoft Azure.

Our team of IoT experts is on hand to learn more about your challenges, and to discuss how Soracom can help at every stage of your product development lifecycle.



**No  
Lock In's**



**Flexible  
Plans**



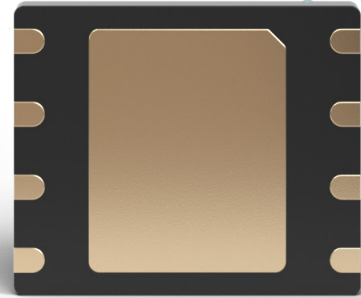
**Cloud  
Agnostic**



**Total  
Visibility**

**You create. We connect.**

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**Soracom eSIMs** are designed for mass-production, and help tech innovators connect devices to the cloud over cellular at scale.

Built to withstand temperatures ranging from  $-40^{\circ}\text{C}$  to  $+105^{\circ}\text{C}$  – and with data retention of up to 15 years – Soracom eSIMs ensure that devices stay connected in even the most extreme environments.

## Features

- Cellular data plans for 2G, 3G, 4G LTE and Cat-M1 with coverage in 180 countries
- Pay-as-you-go pricing – only ever pay for the data you use
- A secure IoT connection
- Direct integration with AWS, Azure, and Google Cloud
- Easy network control and management with the Soracom User Console and API

**Questions?** Visit [soracom.io](https://soracom.io) for more information.

## IoT eSIM Technical Specifications

Software Specifications
Java Card 3.0.2
3GPP Release 11
OTA over SMS (SCP80)
OTA over HTTPS: Global Platform 2.2 amendment B (SCP81)
Java Card Cryptographic APIs ● CRC16, CRC32 ● DES, 3DES ● AES 128/256 bits
Soracom Subscription Container applet
Soracom Local Information applet

Hardware Specifications		
Supply voltage	1.62V to 3.3V (Class B/C)	
Operating Temperature	<b>Commercial Grade</b> -25°C to +85°C	<b>Industrial Grade</b> -40°C to +105°C
Data retention	<b>Commercial Grade</b> Up to 10 years at 85°C	<b>Industrial Grade</b> Up to 15 years at 85°C 10 years at 105°C
NVM Endurance	<b>Commercial Grade</b> 100,000 cycles 85°C	<b>Industrial Grade</b> 500,000 cycles 105°C
ESD Protection	<b>Commercial Grade</b> TS-MA->4kv	<b>Industrial Grade</b> TB-MA->4kv
Ruggedized Form Factor MFF2	TS-MA-HA-CA-VA- SA-RA-UB	TB-MA-HA-CA-VA- SA-RA-UB
Compliance	RoHS compliant	

## IoT eSIM Orderable Quantity

Product Code	Product Description	Soracom Part Number	Number of SIMs per reel	Form Factor	SIM Grade
SGECL01	Global multicarrier Embedded SIM Commercial Grade** (Air plan01s)	SGECL01-01-1000	1,000	MFF2	Commercial
		SGECL01-01-3000	3,000		
SGEIL01	Global multicarrier Embedded SIM Industrial Grade** (Air plan01s)	SGEIL01-01-100*	100		Industrial
		SGEIL01-01-1000	1,000		
		SGEIL01-01-3000	3,000		

\* Also referred to as the **eSIM Mini Reel**. The smaller batch size makes this reel perfect for prototyping and testing when you are at the beginning of your IoT journey.

\*\* SGECL01 and SGEIL01 eSIMs are not eUICC compatible, they use Subscription Containers to manage multiple IMSI profiles (see below). However, Soracom also has eUICC-enabled eSIMs. Contact us directly for more information.

## Leveraging Subscription Containers (Multi IMSI)

**All of the advantages of eUICC without any of its major drawbacks**

When soldering an eSIM into a device, you want to know that you're future proofed and can avoid situations where you're forced to make device updates in the field.

Subscription Containers is how Soracom implements a sophisticated approach to Multi IMSI eSIMs. Manage subscriptions for deployed eSIM enabled devices with OTA updates and automatically prioritize network usage that maximizes extra coverage and lower cost. This allows the same eSIM to reach new markets or access lower rates without any extra work.

Questions? Visit [soracom.io](https://soracom.io) for more information.

## Global multicarrier Embedded SIM Commercial Grade MFF2 (Air plan01s), SGECL01

<b>Software Features</b>	<ul style="list-style-type: none"><li>• Java Card™ 3.0.2</li><li>• 3GPP Release 12</li><li>• Telecom Applications<ul style="list-style-type: none"><li>○ USIM</li><li>○ SIM</li></ul></li><li>• OTA<ul style="list-style-type: none"><li>○ OTA over SMS (SCP80)</li><li>○ OTA over HTTPs: Global Platform 2.2 amendment B (SCP81)</li></ul></li><li>• Java Card™ Cryptographic APIs<ul style="list-style-type: none"><li>○ CRC32</li><li>○ DES, 3DES</li><li>○ AES 128 bits, 256 bits</li></ul></li><li>• SIM applets<ul style="list-style-type: none"><li>○ SORACOM Subscription Container applet</li><li>○ SORACOM Local Information applet</li></ul></li><li>• Low Power<ul style="list-style-type: none"><li>○ Suspend UICC during eDRX/PSM: enabled</li></ul></li></ul>
<b>Hardware Features</b>	<ul style="list-style-type: none"><li>• Supply voltage 1.62V to 5.5V (Class A/B/C)</li><li>• Temperature Range: Operating -25°C to +85°C</li><li>• Data Retention: Up to 10 years at 85°C</li><li>• NVM Endurance: Up to 100,000 Cycles/page @ 85°C</li><li>• ESD Protection &gt; 4kv</li><li>• Ruggedized Form Factor MFF2 (ETSI TS 102 671 compliancy): TS-MA-HA-CA-VA-SA-RA-UB</li><li>• ROHS compliance</li></ul>

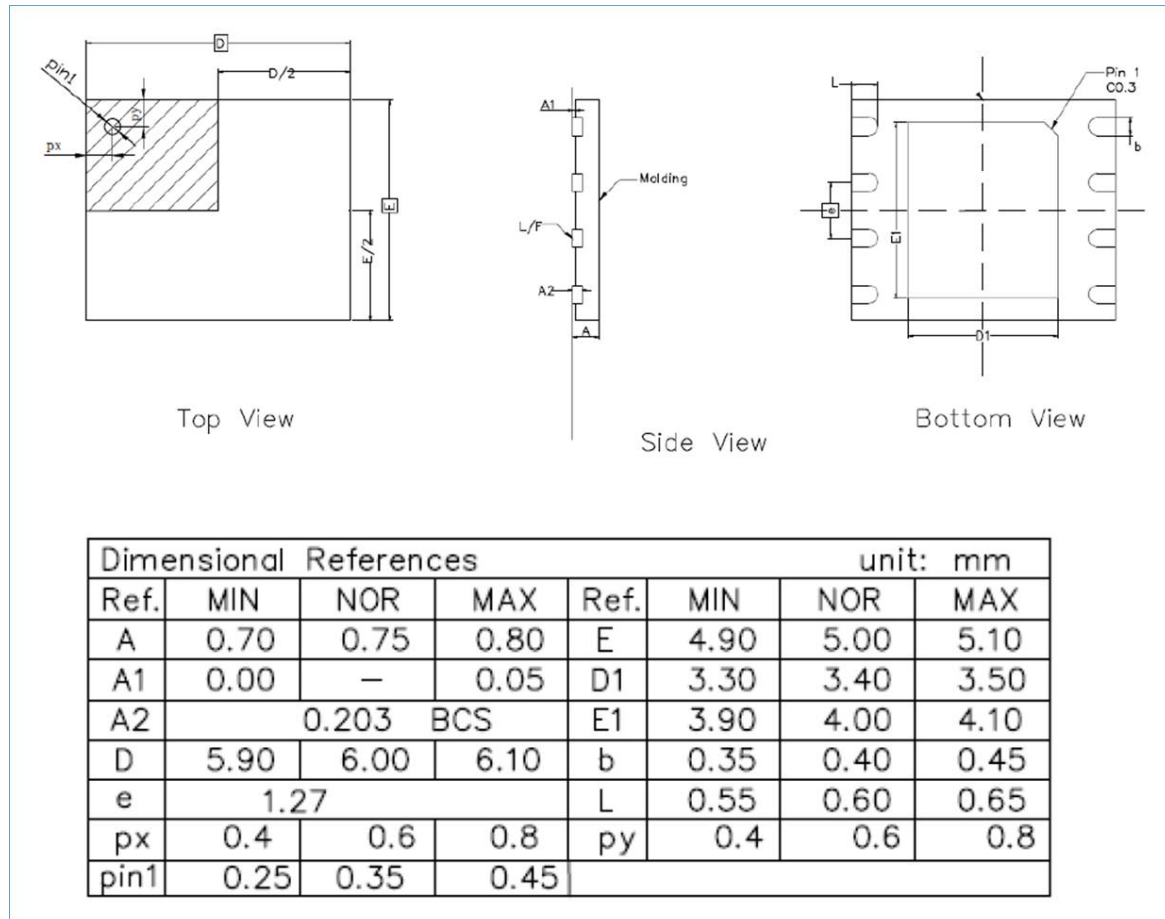
## Global multicarrier Embedded SIM Industrial Grade MFF2 (Air plan01s), SGEIL01

<b>Software Features</b>	<ul style="list-style-type: none"><li>• Java Card™ 3.0.2</li><li>• 3GPP Release 11</li><li>• Telecom Applications<ul style="list-style-type: none"><li>○ USIM</li><li>○ SIM</li></ul></li><li>• OTA<ul style="list-style-type: none"><li>○ OTA over SMS (SCP80)</li><li>○ OTA over HTTPs: Global Platform 2.2 amendment B (SCP81)</li></ul></li><li>• Java Card™ Cryptographic APIs<ul style="list-style-type: none"><li>○ CRC16, CRC32</li><li>○ DES, 3DES</li><li>○ AES 128 bits, 256 bits</li></ul></li><li>• SIM applets<ul style="list-style-type: none"><li>○ SORACOM Subscription Container applet</li><li>○ SORACOM Local Information applet</li></ul></li><li>• Low Power<ul style="list-style-type: none"><li>○ Suspend UICC during eDRX/PSM: enabled</li></ul></li></ul>
<b>Hardware Features</b>	<ul style="list-style-type: none"><li>• Supply voltage 1.62V to 5.5V (Class A/B/C)</li><li>• Temperature Range: Operating -40°C to +105°C</li><li>• Data Retention: 10 years at 105°C</li><li>• NVM Endurance: Up to 500,000 Cycles/page @ 105°C</li><li>• ESD Protection &gt; 4kv</li><li>• Ruggedized Form Factor MFF2 (ETSI TS 102 671 compliancy): TB-MA-HA-CA-VA-SA-RA-UB</li><li>• ROHS compliance</li></ul>

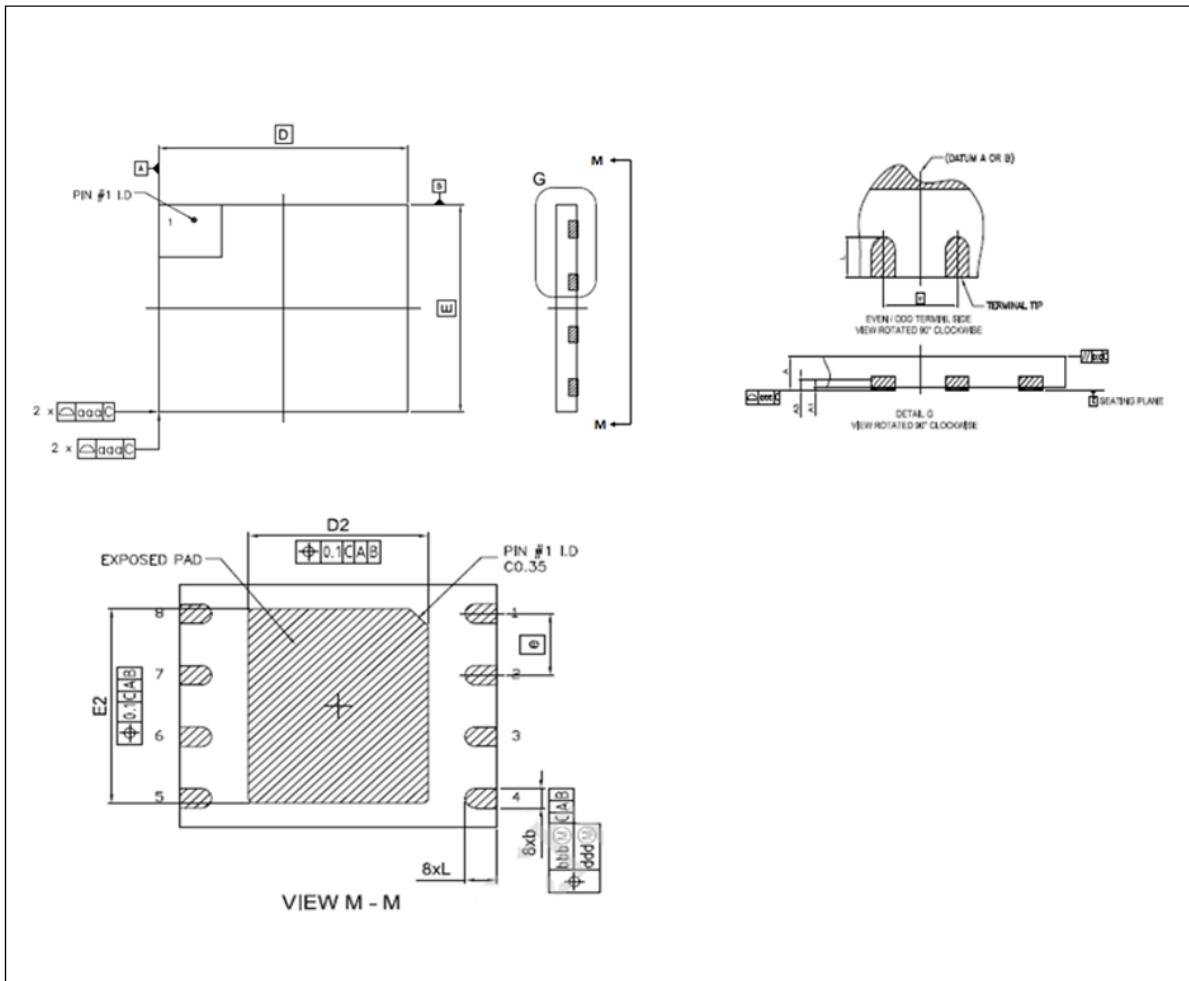
## MFF2 Packaging Datasheet

This section provides specific information for concerning the SMD package used by SIM cards in M2M communications. This SMD package attributes are compliant with ETSI TS 102 671 specifications and is called M2M Form Factor 2 (MFF2).

### Package Mechanical Data and Outline for SGECLO1



# Package Mechanical Data and Outline for SGEI01



DIM	MIN	NOM	MAX	NOTES
A	0.550	0.600	0.650	1 Dimensioning & tolerancing confirm to asme y14.5-1994. 2 All dimensions are in millimeters. angles are in degrees. 3 Dimensions b applies to metallized terminal. 4 Coplanarity applies to the exposed heat slug as well as the terminal. 5 Radius on terminal is optional.
A1	0.00		0.05	
A3	0.203 REF			
b	0.30	0.40	0.50	
D	5.85	6.00	6.15	
E	4.85	5.00	5.15	
D2	3.30	3.40	3.50	
E2	3.90	4.00	4.10	
c	1.27 BSC			
L	0.45	0.60	0.75	
aaa	0.10			
bbb	0.10			
ccc	0.10			
ddd	0.05			
ccc	0.08			

## Package Pinout and mapping of Contacts

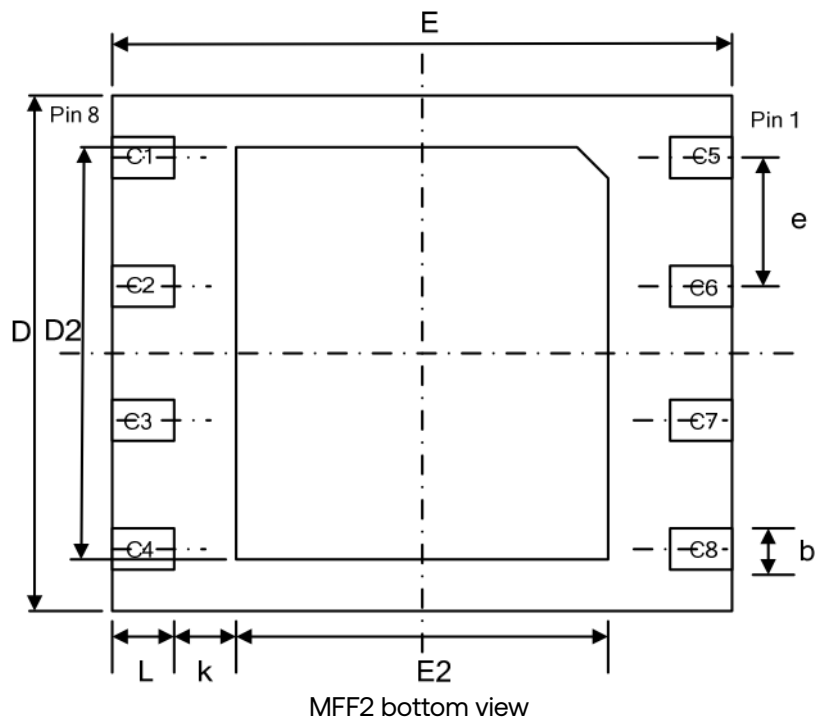
Common for all the eSIM products.

Pin assignments for the contacts C1 to C8 are defined as per ETSI TS 102.221 and TS 102.671.

Pin #	ISO 7816	Signal	Purpose
1 (Index)	C5	GND	Ground
2	C6	NC	Reserved
3	C7	I/O	Input or Output for ISO interface
4	C8	NC	Reserved

Pin #	ISO 7816	Signal	Purpose
5	C4	NC	Reserved
6	C3	CLK	Clock signal input
7	C2	RST	Reset signal input
8	C1	VCC	Supply power input

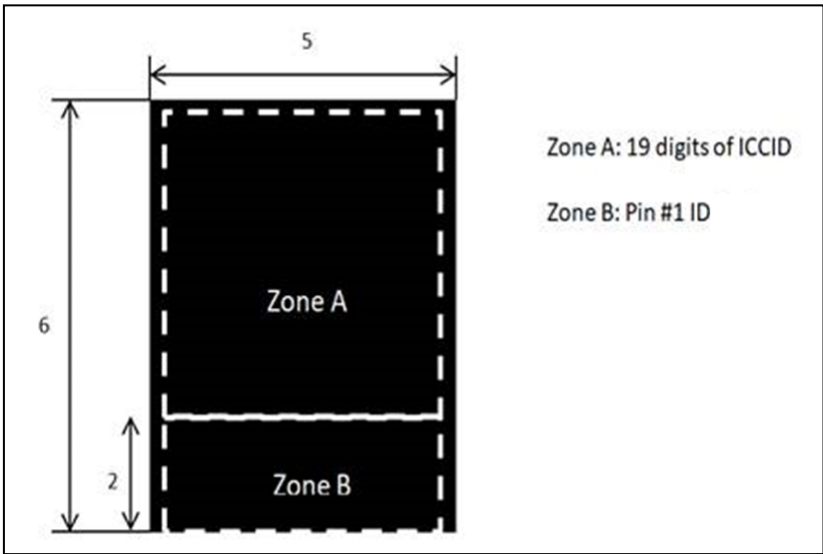
NC: Not physically/electrically connected



The contacts shall be located on the front of the card. The dimensions are referenced to the left and upper edges of the front surface of the card as defined in ISO/IEC 7810. Each numbered contact shall be assigned as specified in ISO/IEC 7816-3 where C4 and C8 are not connected (NC). Unused contact areas shall be either non-conductive or electrically isolated from any other contact area to avoid potential short circuits in interface devices.

# Laser Markings

## Laser Markings for SGECL01



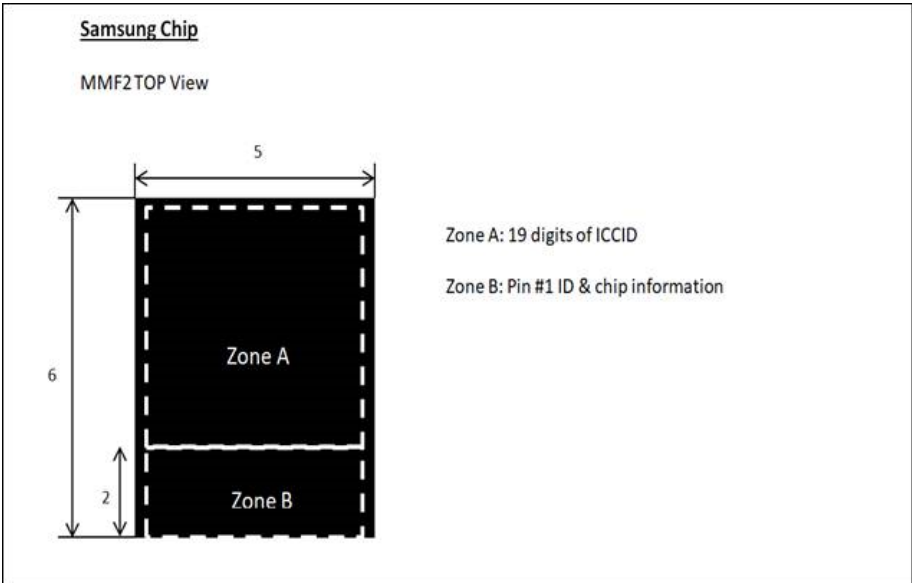
ZONE A: ICCID (19 digits) is printed in 4 lines.

Bottom line (ZONE B)

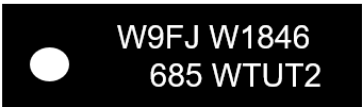


Pin #1 Index is made of only a DOT

## Laser Markings for SGEIL01



ZONE A: ICCID (19digits) is printed in 4 lines.  
ZONE B: (Fixed Markings): This area is not customizable and will be used according to supply source.



Dot and IC vendor specific codes are printed.



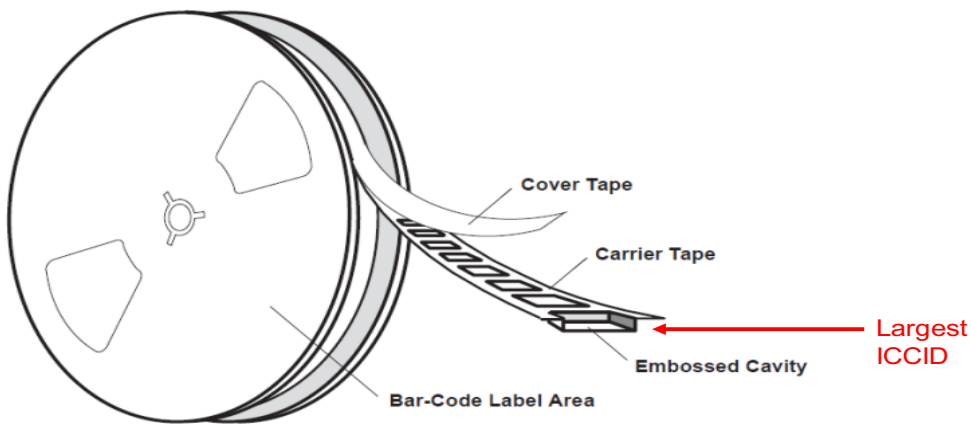
## Tape and Reel Packing

Common for both eSIM and eUICC.

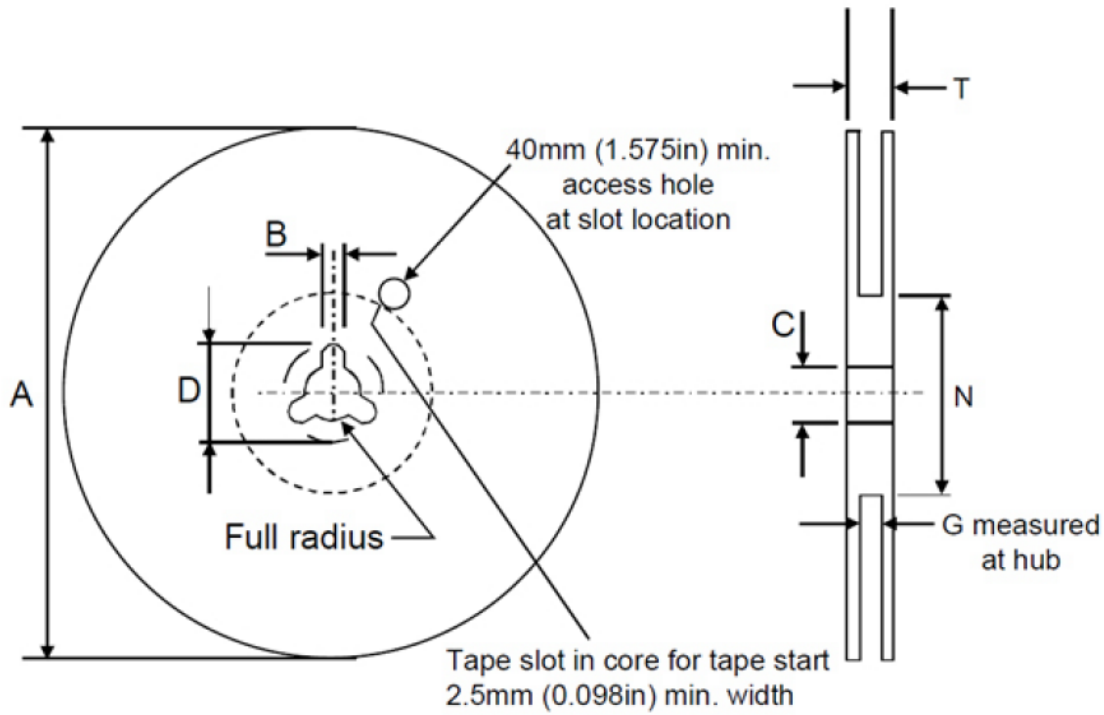
Surface-mount packages are supplied with Tape and Reel packing.

- Quantity per reel: 3000 units
- Material: Styrofoam, electrically conductive
- Surface resistance:  $10^2 < R < 10^{12}$  ohms

Reel size	Tape size	A Max.	B Min.	C	D Min.	G Max.	N Min.	T Max.	Unit
13"	12 mm	330	1.5	$13 \pm 0.25$	20.2	12.6	100	18.4	mm



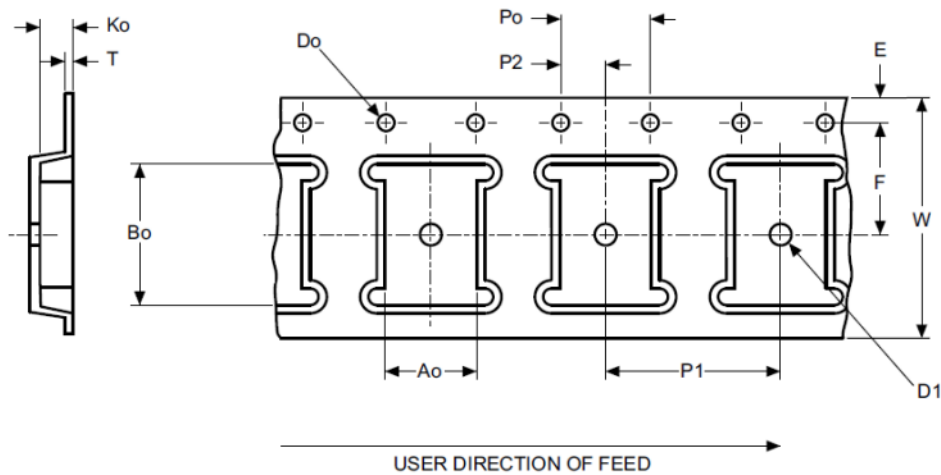
Note: the smallest ICCID is the most inside, and the largest ICCID is the outmost.



### Embossed Carrier Tape

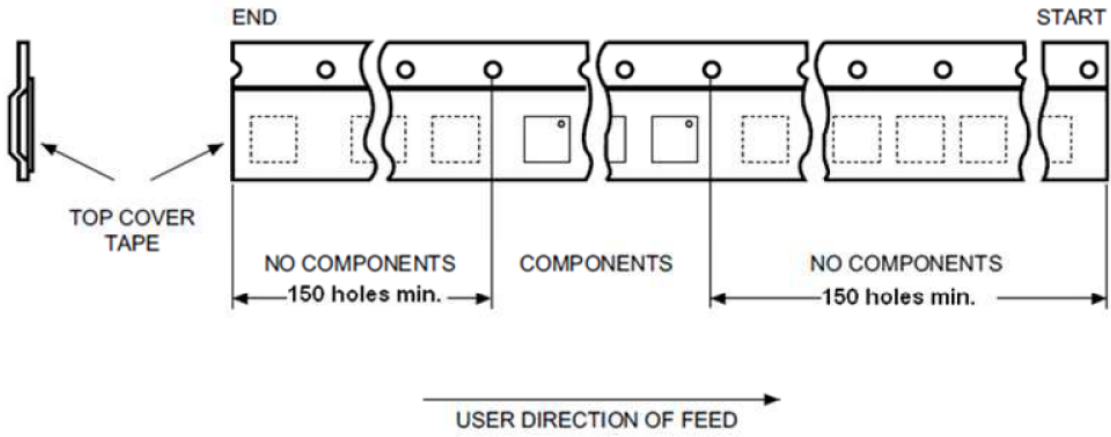
Typically, the carrier tape is constructed from a polystyrene (PS) or PS-laminate film. The uniform film thickness is 0.2mm to 0.4mm, depending on the size and weight of the component carried by the tape.

- Cover tape's surface resistance:  $10^5$  Ohms/sq
- Carrier tape's surface resistance:  $10^5$ - $10^9$  Ohms/sq



Package	A0	B0	K0	D1 Min.	P1	P2	D0	P0	E	F	W	T Max.	Unit
MFF2	5.3 ±0.1	6.3 ±0.1	1.2 ±0.1	1.5	8 ±0.1	2 ±0.1	1.55 ±0.05	4 ±0.1	1.75 ±0.1	5.5 ±0.1	12 ±0.3	0.3 ±0.05	mm

## Leader and Trailer



**Note:** *Min. trailer length : 160 mm and min. leader length: 400 mm*  
*100 pc will not have leader/trailer.*

## Moisture Sensitivity

Plastic IC packages absorb moisture from the surrounding environment. This is a typical characteristic of the materials (mold compound and die attach) used in the construction of plastic packages.

The moisture inside the package increases or decreases to reach the relative humidity (RH) of the surrounding environment. Weight gain/loss analysis is used to determine the time it takes for a package to reach moisture saturation or the time required for removing it. This information is used to specify maximum exposure times and minimum dry-baking time.

### Moisture Sensitivity Levels for SGECLO1

Moisture Sensitivity Levels

FLOOR LIFE		SOAK REQUIREMENTS			
		STANDARD		ACCELERATED EQUIVALENT	
TIME	CONDITIONS	TIME (hours)	CONDITIONS	TIME (hours)	CONDITIONS
168 hours	≤30°C/60% RH	192 +5/-0	30°C/60% RH	40 +1/-0	60°C/60% RH

### Moisture Sensitivity Levels for SGEIL01

LEVEL	FLOOR LIFE			SOAK TIME		
	CONDITIONS		TIME	TIME(HOURS)	CONDITIONS	
	TEMPERATURE (°C)	RH (%)			TEMPERATURE (°C)	RH (%)
3	≤30	60	168 hours	192	30	60